

16-channel Constant Current LED Sink Driver

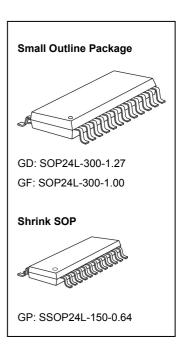
Features

- 16 constant-current output channels
- Constant output current invariant to load voltage change:
 Constant output current range:
 - $3-45mA@V_{DD}=5V;$
 - 3-30mA@V_{DD}=3.3V
- Excellent output current accuracy:

between channels: $\pm 3\%$ (max.), and

between ICs: ±6% (max.)

- Output current adjusted through an external resistor
- Fast response of output current, OE (typ.): 100 ns
- Staggered output delay
- 25MHz clock frequency
- Schmitt trigger input
- 3.3V/ 5V supply voltage
- "Pb-free & Green" Package



Current Accuracy		Conditions
Between Channels	Between ICs	Conditions
< ±3%	< ±6%	I_{OUT} =3mA~30mA@V _{DS} =0.8V; V _{DD} =3.3V I_{OUT} =3mA~45mA@V _{DS} =0.8V; V _{DD} =5.0V

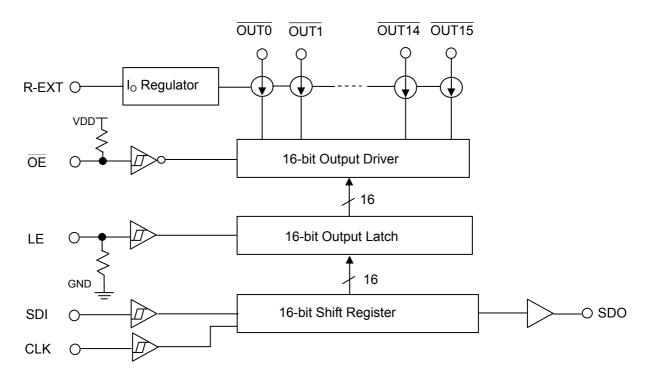
Product Description

With PrecisionDrive™ technology, MBI5025 is designed for LED displays which require to operate at low current and to match the luminous intensity of each channel. It provides supply voltage and accepts CMOS logic input at 3.3V and 5.0V to meet the trend of low power consumption. MBI5025 contains a serial buffer and data latches which convert serial input data into parallel output format. At MBI5025 output stage, sixteen regulated current ports are designed to provide uniform and constant current sinks for driving LEDs within a large range of V_F variations.

MBI5025 provides users with great flexibility and device performance while using MBI5025 in their system design for LED display applications, e.g. LED panels. It accepts an input voltage range from 3V to 5.5V and maintains a constant current up from 3 mA to 45 mA determined by an external resistor, R_{ext}, which gives users flexibility in controlling the light intensity of LEDs. MBI5025 guarantees to endure maximum 17V at the output port. The high clock frequency, 25 MHz, also satisfies the system requirements of high volume data transmission.

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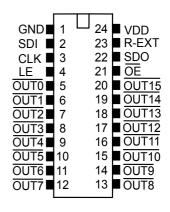
Block Diagram



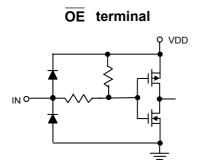
Terminal Description

Pin No.	Pin Name	Function
1	GND	Ground terminal for control logic and current sink
2	SDI	Serial-data input to the shift register
3	CLK	Clock input terminal for data shift on rising edge
		Data strobe input terminal
4	LE	Serial data is transferred to the output latch when LE is high. The data is latched when LE goes low.
5~20	OUT0∼OUT15	Constant current output terminals
		Output enable terminal
21	ŌĒ	When (active) low, the output drivers are enabled; when high, all output drivers are turned OFF (blanked).
22	SDO	Serial-data output to the following SDI of next driver IC. SDO signal change on rising edge of CLK.
23	R-EXT	Input terminal used to connect an external resistor for setting up output current for all output channels
24	VDD	3.3V/5V supply voltage terminal

Pin Configuration

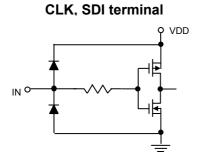


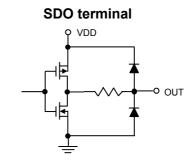
Equivalent Circuits of Inputs and Outputs



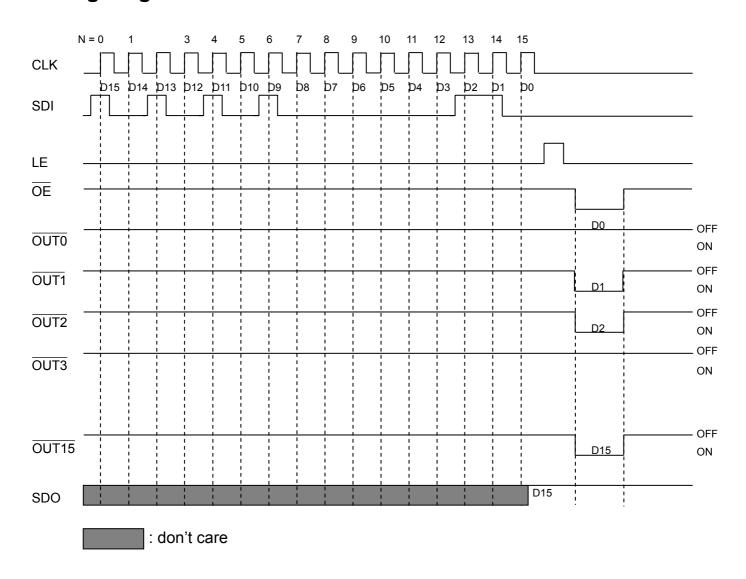
IN O VDD

LE terminal





Timing Diagram



Truth Table

CLK	LE	ŌĒ	SDI	OUT0 OUT 7 OUT 15	SDO
	Н	L	D _n	Dn Dn - 7 Dn - 15	D _{n-15}
<u> </u>	L	L	D _{n+1}	No Change	D _{n-14}
	Н	L	D _{n+2}	<u>Dn + 2</u> <u>Dn - 5</u> <u>Dn - 13</u>	D _{n-13}
—	Х	L	D _{n+3}	Dn+2Dn-5Dn-13	D _{n-13}
—	Х	Н	D _{n+4}	Off	D _{n-13}

Maximum Ratings

Characteristic		Symbol	Rating	Unit
Supply Voltage		V_{DD}	0~7.0	V
Input Voltage		V _{IN}	-0.4~V _{DD} +0.4	V
Output Current		I _{OUT}	+90	mA
Sustaining Voltage at OUT I	Port	V _{DS}	-0.5~+17.0	V
GND Terminal Current		I _{GND}	+1000	mA
	GD-type		2.88	
Power Dissipation (On PCB, Ta=25°C)	GF-type	P _D	2.35	W
(6.1. 65, 14 26 6)	GP-type		1.76	
	GD-type		46.60	
Thermal Resistance (On PCB, Ta=25°C)	GF-type	R _{th(j-a)}	53.28	°C/W
(3 32, 12 20 0)	GP-type		70.90	
Operating Temperature		T _{opr}	-40~+85	°C
Storage Temperature		T _{stg}	-55~+150	°C

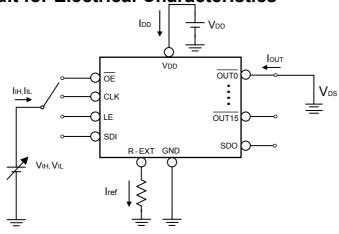
Electrical Characteristics (V_{DD} = 5.0V)

Charact	eristics	Symbol	Cond	lition	Min.	Тур.	Max.	Unit
Supply Voltag	е	V_{DD}	-	-	4.5	5.0	5.5	V
Sustaining Vo Ports	Itage at OUT	V _{DS}	OUT0 ~ OUT1	5	-	-	17.0	V
		I _{OUT}	Refer to "Test C Electrical Chara		3	-	45	mA
Output Curren	t	I _{OH}	SDO		-	-	-1.0	mA
		I _{OL}	SDO		-	-	1.0	mA
Innut Valtage	"H" level	V _{IH}	Ta =-40~85°C		0.7*V _{DD}	-	V_{DD}	V
Input Voltage	"L" level	V _{IL}	Ta =-40~85°C		GND	-	0.3*V _{DD}	V
Output Leakag	e Current	I _{OH}	V _{DS} =17.0V		-	-	0.5	μΑ
Output Valtage	e SDO	V _{OL}	I _{OL} =+1.0mA		-	-	0.4	V
Output Voltage	5 500	V _{OH}	I _{OH} =-1.0mA		4.6	-	-	V
Output Curren	1 1	I _{OUT1}	V _{DS} =1.0V R _{ext} =1860Ω		-	10	-	mA
Current Skew		dl _{OUT1}	I_{OL} =10mA V_{DS} =1.0V R_{ext} =1860 Ω		-	±1	±3	%
Output Curren	t 2	I _{OUT2}	V _{DS} =1.0V	R_{ext} =744 Ω	-	25	-	mA
Current Skew		dl _{OUT2}	I _{OL} =25mA V _{DS} =1.0V	R _{ext} =744Ω	-	±1	±3	%
Output Curren		%/dV _{DS}	V _{DS} within 1.0V	and 3.0V	-	±0.1	-	%/V
Output Curren Supply Voltage		%/dV _{DD}	V _{DD} within 4.5V	and 5.5V	-	±1	-	%/V
Pull-up Resisto	or	R _{IN} (up)	Ō	 E	250	500	800	ΚΩ
Pull-down Res	istor	R _{IN} (down)	L	E	250	500	800	ΚΩ
		I _{DD} (off) 1	R_{ext} =Open, $\overline{\text{OUT0}} \sim \overline{\text{OUT15}}$ =Off R_{ext} =1860 Ω , $\overline{\text{OUT0}} \sim \overline{\text{OUT15}}$ =Off		-	2.4	5.0	
	"OFF"	I _{DD} (off) 2			-	4.3	7.0	
Supply Current		I _{DD} (off) 3		T0 ~ OUT15 =Off	-	5.7	9.0	mA
Junion	"ON!"	I _{DD} (on) 1	$R_{\text{ext}}=1860\Omega, \overline{\text{OU}}$	T0 ~ OUT15 =On	-	4.6	8.5	
	"ON"	I _{DD} (on) 2		T0 ~ OUT15 =On	-	6.0	9.5	

Electrical Characteristics (V_{DD} = 3.3V)

Charact	eristics	Symbol	Cond	lition	Min.	Тур.	Max.	Unit
Supply Voltag	е	V_{DD}	-	-	3.0	3.3	4.5	V
Sustaining Vo Ports	Itage at OUT	V _{DS}	OUT0 ~ OUT15		-	-	17.0	V
		I _{OUT}	Refer to "Test C Electrical Charac		3	-	30	mA
Output Curren	:	I _{OH}	SDO		-	-	-1.0	mA
		I _{OL}	SDO		-	-	1.0	mA
Innut Valtage	"H" level	V _{IH}	Ta=-40~85°C		0.7*V _{DD}	-	V_{DD}	V
Input Voltage	"L" level	V _{IL}	Ta=-40~85°C		GND	-	0.3*V _{DD}	V
Output Leakag	e Current	I _{OH}	V _{DS} =17.0V		-	-	0.5	μA
Outrout Valtage	000	V _{OL}	I _{OL} =+1.0mA		-	-	0.4	V
Output Voltage	SDO	V _{OH}	I _{OH} =-1.0mA		2.9	-	-	V
Output Curren	1	I _{OUT1}	V _{DS} =1.0V	R _{ext} =6200Ω	-	3	-	mA
Current Skew		dl _{OUT1}	I _{OL} =3mA V _{DS} =1.0V	R _{ext} =6200Ω	-	±1	±3	%
Output Curren	2	I _{OUT2}	V _{DS} =1.0V	R _{ext} =744Ω	-	25	-	mA
Current Skew		dl _{OUT2}	I _{OL} =25mA V _{DS} =1.0V	R _{ext} =744Ω	-	±1	±3	%
Output Curren		%/dV _{DS}	V _{DS} within 1.0V a	and 3.0V	-	±0.1	-	%/V
Output Curren Supply Voltage	vs.	%/dV _{DD}	V _{DD} within 3.0V a	and 4.5V	-	±1	-	%/V
Pull-up Resisto	or	R _{IN} (up)	ō	E	250	500	800	ΚΩ
Pull-down Res	istor	R _{IN} (down)	L	.E	250	500	800	ΚΩ
		I _{DD} (off) 1	R _{ext} =Open, OUT		-	1.8	5.0	
	"OFF" $I_{DD}(off) \ 2 R_{ext} = 6200\Omega, \overline{OUT0} \sim \overline{OUT15} = Off$		-	4.0	7.0			
Supply Current		I _{DD} (off) 3	, one		-	5.2	8.5	mA
Junion	"ON!"	I _{DD} (on) 1	R_{ext} =6200 Ω , $\overline{\text{OU}}$	<u>Γ0</u> ~ <u>OUT15</u> =On	-	4.5	7.0	
	"ON"	I _{DD} (on) 2	R_{ext} =744 Ω , \overline{OUT}	OUT15 =On	-	5.5	8.5	

Test Circuit for Electrical Characteristics



Switching Characteristics (V_{DD} = 5.0V)

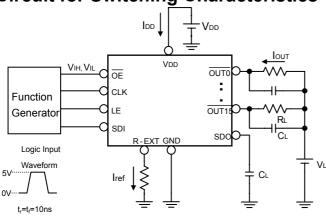
Character	istics	Symbol	Condition	Min.	Тур.	Max.	Unit
	CLK-OUT2n	4		-	50	70	ns
Propagation Delay Time ("L" to "H")	CLK-OUT2n + 1	t _{pLH1}		-	35	55	ns
	LE-OUT2n			-	50	70	ns
	LE-OUT2n + 1	t _{pLH2}		-	35	55	ns
	OE - OUT2n	t		-	50	70	ns
	OE - OUT2n + 1	t _{pLH3}		-	35	55	ns
	CLK-SDO	t _{pLH}		-	20	40	ns
	CLK-OUT2n			-	90	110	ns
	CLK-OUT2n + 1	t _{pHL1}		-	75	95	ns
	LE-OUT2n	t _{pHL2}		-	90	110	ns
Propagation Delay Time ("H" to "L")	LE-OUT2n + 1		V_{DD} =5.0 V V_{DS} =1.0 V V_{IH} = V_{DD} V_{IL} =GND V_{E} =930 Ω V_{L} =4.5 V	-	75	95	ns
	OE - OUT2n	t _{pHL3}		-	90	110	ns
	OE - OUT2n + 1			-	75	95	ns
	CLK-SDO	t _{pHL}		-	20	40	ns
	CLK	t _{w(CLK)}	$R_L=162 \Omega$	20	-	-	ns
Pulse Width	LE	t _{w(L)}	C _L =10 pF	20	-	-	ns
	ŌĒ	$t_{w(OE)}$		-	100	-	ns
Hold Time for LE		t _{h(L)}		30	-	-	ns
Setup Time for LE		t _{su(L)}		5	-	-	ns
Hold Time for SDI	Hold Time for SDI			5	-	-	ns
Setup Time for SDI		t _{su(D)}		3	-	-	ns
Maximum CLK Rise Time		t _r		-	-	500	ns
Maximum CLK Fall Time		t _f		-	-	500	ns
SDO Rise Time		t _{r,SDO}		-	10	-	ns
SDO Fall Time		$t_{f,SDO}$		-	10	-	ns
Output Rise Time of Outp	ut Ports	t _{or}		-	40	-	ns
Output Fall Time of Outpu	t Ports	t _{of}		-	55	-	ns

^{*} Among output channels exist 15ns delay time between odd number $\overline{OUT2n+1}$ (e.g.:Bit1/Bit3/Bit5...)and even number $\overline{OUT2n}$ (ex: Bit0/Bit2/Bit4...). MBI5025 has a built-in staggered circuit to perform delay mechanism, by which the even and odd output ports will be turned on at a different time so that the instant current from the power line will be lowered.

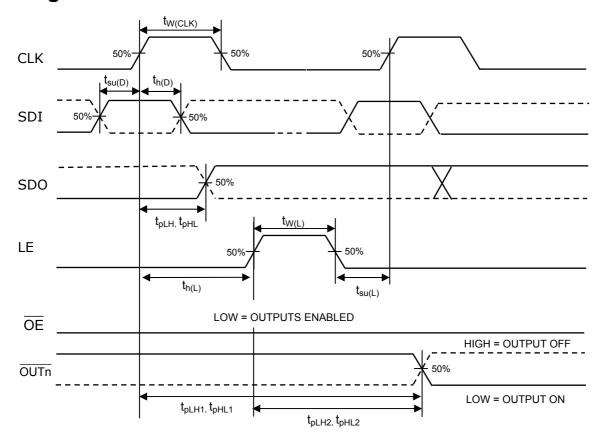
Switching Characteristics (V_{DD}= 3.3V)

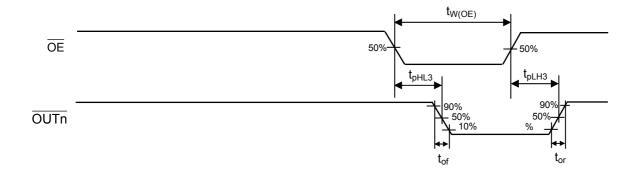
Characteri		Symbol	Condition	Min.	Тур.	Max.	Unit
	CLK-OUT2n	-		_	50	70	ns
Propagation Delay Time ("L" to "H")		t_{pLH1}		_	35	55	ns
	CLK-OUT2n+1				50	70	
	LE-OUT2n	t _{pLH2}		-			ns
	LE-OUT2n + 1			-	35	55	ns
	OE - OUT2n	t_{pLH3}		-	50	70	ns
	OE - OUT2n + 1	PENO		-	35	55	ns
	CLK-SDO	t_{pLH}		-	20	40	ns
	CLK-OUT2n	t		-	115	135	ns
	CLK-OUT2n + 1	t _{pHL1}		-	100	120	ns
Propagation Delay Time ("H" to "L")	LE-OUT2n	t _{pHL2}		-	115	135	ns
	LE-OUT2n + 1		V_{DD} =3.3 V V_{DS} =1.0 V V_{IH} = V_{DD} V_{IL} =GND	_	100	120	ns
	OE - OUT2n	t _{pHL3}		-	105	125	ns
	OE - OUT2n + 1			-	90	110	ns
	CLK-SDO		R_{ext} =930 Ω	-	20	40	ns
	CLK	t _{w(CLK)}	V_L =4.5 V R_L =162 Ω	20	_	-	ns
Pulse Width	LE	t _{w(L)}	C _L =10 pF	20	-	-	ns
	ŌĒ	$t_{w(OE)}$		-	130	-	ns
Hold Time for LE		t _{h(L)}		30	-	-	ns
Setup Time for LE		t _{su(L)}		5	_	-	ns
Hold Time for SDI	Hold Time for SDI			5	_	-	ns
Setup Time for SDI		t _{su(D)}		3	_	-	ns
Maximum CLK Rise Time		t _r		-	_	500	ns
Maximum CLK Fall Time		t _f		-	-	500	ns
SDO Rise Time		t _{r,SDO}		-	10	-	ns
SDO Fall Time		$t_{f,SDO}$		-	10	-	ns
Output Rise Time of Outp	ut Ports	t _{or}		-	40	-	ns
Output Fall Time of Outpu	t Ports	t _{of}		-	60	-	ns

Test Circuit for Switching Characteristics



Timing Waveform



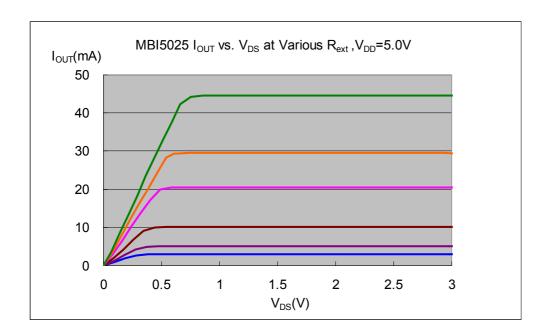


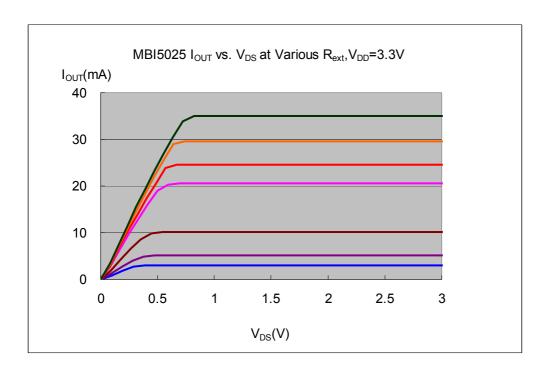
Application Information

Constant Current

To design LED displays, MBI5025 provides nearly no variations in current from channel to channel and from IC to IC. This can be achieved by:

- 1) The maximum current variation between channels is less than ±3%, and that between ICs is less than ±6%.
- 2) In addition, the current characteristic of output stage is flat and users can refer to the figure as shown below. The output current can be kept constant regardless of the variations of LED forward voltages (V_F). This performs as a perfection of load regulation.



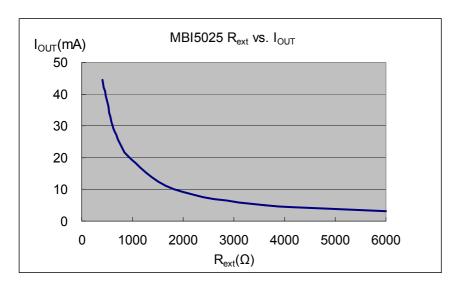


Adjusting Output Current

The output current of each channel (I_{OUT}) is set by an external resistor, R_{ext} . The relationship between I_{OUT} and R_{ext} is shown in the following figure.

Also, the output current can be calculated from the equation:

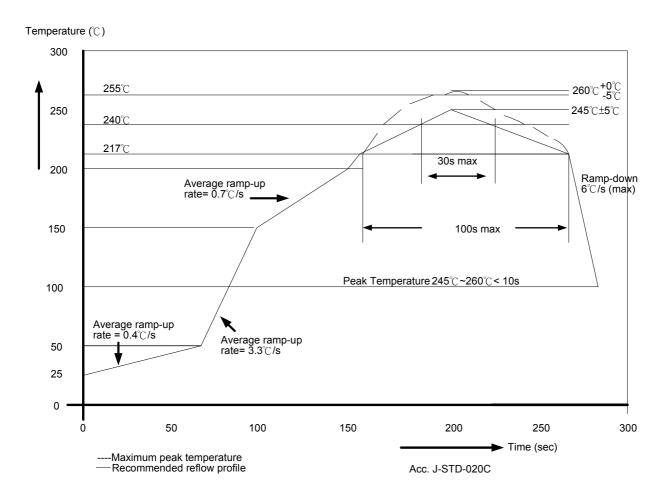
 V_{R-EXT} =1.24V; I_{OUT} = V_{R-EXT} *(1/Rext)x15; R_{ext} =(V_{R-EXT} / I_{OUT})x15



Where R_{ext} is the resistance of the external resistor connected to R-EXT terminal and V_{R-EXT} is the voltage of R-EXT terminal. The magnitude of current (as a function of R_{ext}) is around 25mA at 744 Ω and 10mA at 1860 Ω .

Soldering Process of "Pb-free & Green" Package*

Macroblock has defined "Pb-Free & Green" to mean semiconductor products that are compatible with the current RoHS requirements and selected **100% pure tin** (Sn) to provide forward and backward compatibility with both the current industry-standard SnPb-based soldering processes and higher-temperature Pb-free processes. Pure tin is widely accepted by customers and suppliers of electronic devices in Europe, Asia and the US as the lead-free surface finish of choice to replace tin-lead. Also, it is backward compatible to standard 215°C to 240°C reflow processes which adopt tin/lead (SnPb) solder paste. However, in the whole Pb-free soldering processes and materials, 100% pure tin (Sn), will all require up to 260°C for proper soldering on boards, referring to J-STD-020C as shown below.



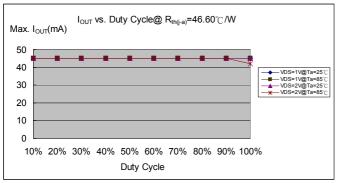
*Note1: For details, please refer to Macroblock's "Policy on Pb-free & Green Package".

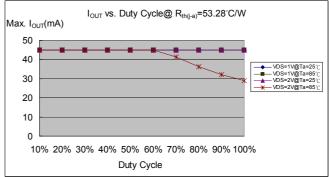
Package Power Dissipation (PD)

The maximum allowable package power dissipation is determined as $P_D(max)=(Tj-Ta)/R_{th(j-a)}$. When 16 output channels are turned on simultaneously, the actual package power dissipation is

 $P_D(act)=(I_{DD}xV_{DD})+(I_{OUT}xDutyxV_{DS}x16)$. Therefore, to keep $P_D(act)\leq P_D(max)$, the allowable maximum output current as a function of duty cycle is:

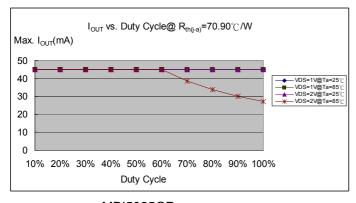
 $I_{OUT} = \{ [(Tj - Ta)/R_{th(j-a)}] - (I_{DD}xV_{DD})\}/V_{DS}/Duty/16, \ where \ Tj = 150 ^{\circ}C.$





MBI5025GD

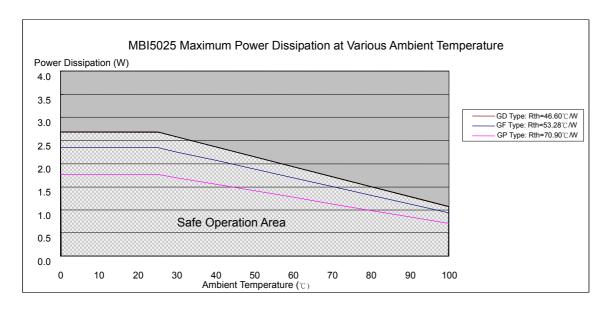
GD MBI5025GF



Condition: I _{OUT} =45mA,16 output Channels		
Device Type R _{th(i-a)} (°C/W)		
GD	46.60	
GF	53.28	
GP	70.90	

MBI5025GP

The maximum power dissipation, $P_D(max)=(Tj-Ta)/R_{th(j-a)}$, decreases as the ambient temperature increases.

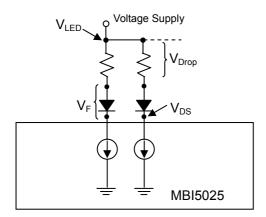


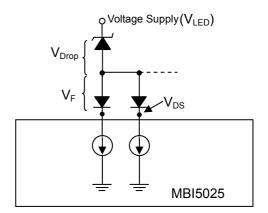
Load Supply Voltage (V_{LED})

MBI5025 are designed to operate with V_{DS} ranging from 0.4V to 0.8V (depending on I_{OUT} =3~45mA) considering the package power dissipating limits. V_{DS} may be higher enough to make $P_{D(act)} > P_{D(max)}$ when V_{LED} =5V and V_{DS} = V_{LED} - V_F , in which V_{LED} is the load supply voltage. In this case, it is recommended to use the lowest possible supply voltage or to set an external voltage reducer, V_{DROP} .

A voltage reducer lets $V_{DS}=(V_{LED}-V_F)-V_{DROP}$.

Resistors or Zener diode can be used in the applications as shown in the following figures.

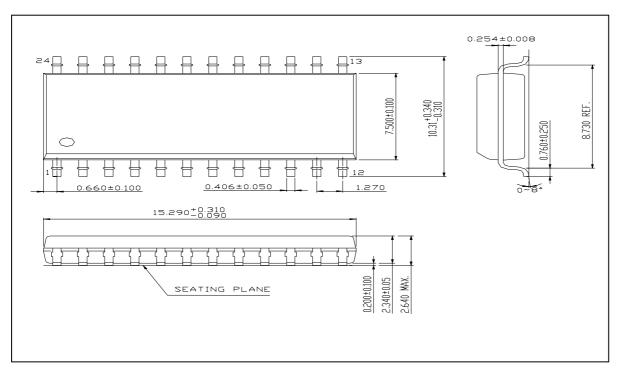




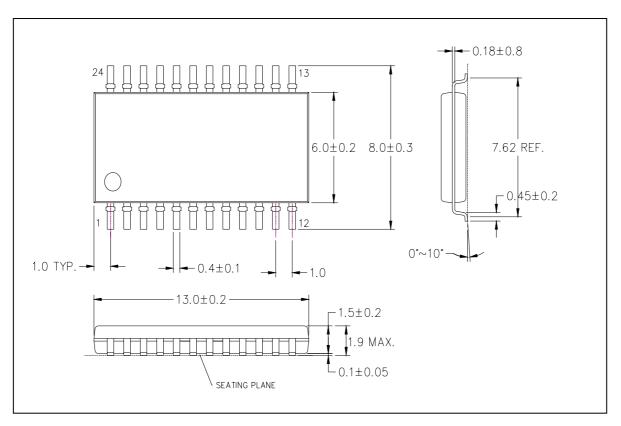
Switching Noise Reduction

LED driver ICs are frequently used in switch-mode applications which always behave with switching noise due to the parasitic inductance on PCB. To eliminate switching noise, refer to "Application Note for 8-bit and 16-bit LED Drivers- Overshoot".

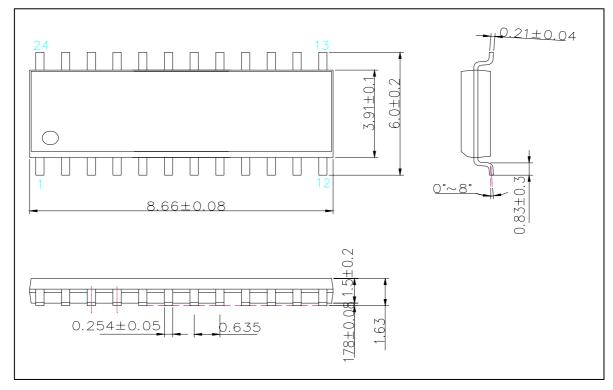
Package Outline



MBI5025GD Outline Drawing

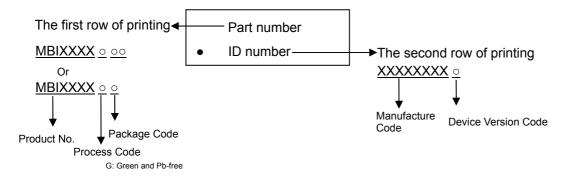


MBI5025GF Outline Drawing



MBI5025GP Outline Drawing

Product Top-mark Information



Product Revision History

Datasheet version	Device version code
V1.00	Α
VA.00	A
VA.01	В

Product Ordering Information

Part Number	"Pb-free & Green" Package Type	Weight (g)
MBI5025GD	SOP24L-300-1.27	0.617
MBI5025GF	SOP24L-300-1.00	0.28
MBI5025GP	SSOP24L-150-0.64	0.11

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